





INA114 Precision Instrumentation Amplifier

1 Features

- Low offset voltage: 50µV maximum for high gains
- Low drift: 0.3µV/°C maximum for high gains
- Low input bias current: 2nA maximum
- High common-mode rejection: 115dB minimum
- Input over-voltage protection: ±40V
- Wide supply range: ±2.25V to ±18V
- Packages: PDIP-8 and SOIC-16

2 Applications

- Surgical equipment
- **Actuator**
- Multifunction relay
- Train control and management
- Trackside signaling and control

3 Description

The **INA114** is low-cost, а general-purpose instrumentation amplifier offering excellent accuracy. The versatile three-op-amp design and small size make this device an excellent choice for a wide range of applications.

A single external resistor sets any gain from 1 to 10,000. Internal input protection withstands up to ±40V without damage.

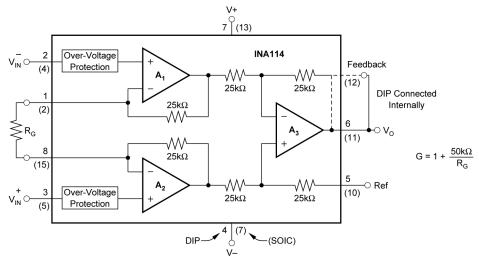
The INA114 is laser trimmed for very low offset voltage (50µV), low drift (0.3µV/°C), and high common-mode rejection (115dB at G = 1000). The device operates with power supplies as low as ±2.25V, allowing use in battery-operated and single 5V supply systems.

The INA114 is available in 8-pin PDIP and 16-pin SOIC surface-mount packages. Both are specified for a temperature range of -40°C to +85°C.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE(2)
INA114	P (PDIP, 8)	9.81mm × 9.43mm
	DW (SOIC, 16)	10.3mm × 10.3mm

- For more information, see Section 10.
- The package size (length × width) is a nominal value and includes pins, where applicable.



Schematic

Table of Contents

1 Features	1	6.1 Application Information	10
2 Applications		7 Typical Applications	
3 Description	1	8 Device and Documentation Support	18
4 Pin Configuration and Functions	<mark>2</mark>	8.1 Receiving Notification of Documentation Updates	18
5 Specifications	3	8.2 Support Resources	18
5.1 Absolute Maximum Ratings	3	8.3 Trademarks	18
5.2 ESD Ratings	3	8.4 Electrostatic Discharge Caution	18
5.3 Recommended Operating Conditions		8.5 Glossary	18
5.4 Thermal Information	3	9 Revision History	
5.5 Electrical Characteristics	4	10 Mechanical, Packaging, and Orderable	
5.6 Typical Characteristics	6		19
6 Application and Implementation	10		

4 Pin Configuration and Functions

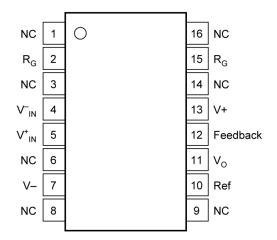


Figure 4-1. DW Package, 16-Pin SOIC (Top View)

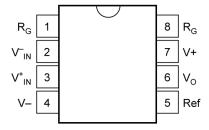


Figure 4-2. P Package, 8-Pin PDIP (Top View)

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
Vs	Supply voltage	Single supply, $V_S = (+V_S)$		36	V
vs	Supply Voltage	Dual supply, $V_S = (+V_S) - (-V_S)$	-18	18	V
	Signal input pins		-40	40	V
Vo	Signal output voltage	Signal output voltage		(+V _S) + 0.5	V
Is	Output short-circuit (to V _S /2)		Continuou	s	
T _A	Operating temperature		-40	125	°C
TJ	Junction temperature			150	°C
T _{stg}	Storage temperature		-40	125	°C

⁽¹⁾ Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

5.2 ESD Ratings

				VALUE	UNIT
	,		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±1500	.,
1	(ESD)	Electrostatic discharge	Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1500	V

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V	Supply voltage	Single supply, $V_S = (+V_S)$	4.5	36	\/
Vs	Supply voltage	Dual supply, $V_S = (+V_S) - (-V_S)$	±2.25	±18	V
T _A	Specified temperature		-40	85	°C

5.4 Thermal Information

		INA	.114	
	THERMAL METRIC ⁽¹⁾	DW (SOIC)	UNIT	
		16 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	74.2	110.2	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



5.5 Electrical Characteristics

at $T_A = 25^{\circ}C$, $V_S = \pm 15V$, $R_L = 2k\Omega$, $V_{REF} = 0V$, and G = 1 (unless otherwise noted)

	PARAMETER	TEST (CONDITIONS		MIN	TYP	MAX	UNIT
INPUT								
			INA114BP, I	BU		±10 + 20/G	±50 + 150/G	
Vos	Offset voltage	RTI	INA114AP,	AU		±25 + 30/G	±125 + 500/G	μV
	0	T 4000 1 10500 PTI	INA114BP, I	BU		±0.1 + 0.5/G	±0.3 + 5/G	1400
	Offset voltage drift	$T_A = -40$ °C to +85°C, RTI	INA114AP, AU			±0.25 + 5/G	±1 + 10/G	μV/°C
	Long-term stability					±0.2 + 0.5/G		μV/mo
	Differential impedance					100 6		GΩ pF
	Common-mode impedance					100 6		GΩ pF
	Operating input voltage				(V-) + 4		(V+) - 4	V
PSRR	Power-supply rejection ratio	RTI, ±2.25V to ±18V				0.5 + 2/G	3 + 10/G	μV/V
			G = 1	INA114BP, BU	80	96		dB
	Common-mode rejection ratio		G = 1	INA114AP, AU	75	90		
			G = 10 G = 100	INA114BP, BU	96	115		dB
CMRR		At dc to 60Hz, RTI, V _{CM} = ±10V,		INA114AP, AU	90	106		
CIVIRR		$\Delta R_S = 1k\Omega$		INA114BP, BU	110	120		
			G - 100	INA114AP, AU	106	110		
			G = 1000	INA114BP, BU	115	120		
			INA114AP, AU		106	110		
BIAS C	URRENT							
В	Input bias current	$V_{CM} = V_S / 2$	INA114BP, I	BU		±0.5	±2	nA
'B	input bias current	INA114AP, AU			±0.5	±5		
	Input bias current drift	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	INA114BP, I	BU		±8		pA/°C
	input bias current unit	1A - 40 0 to 100 0	INA114AP,	AU		±8		pr v O
los	Input offset current	$V_{CM} = V_S / 2$	INA114BP, I	BU		±0.5	±2	nA
108	input onset current	VCM - VS / Z	INA114AP, AU			±0.5	±5	177
	Input offset current drift	$T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$	INA114BP, I	BU		±8		pA/°C
	impat onoot ourront and	14 10 0 10 100 0	INA114AP,	AU		±8		p, t 0
NOISE	VOLTAGE							
		f = 10Hz $G = 1000, R_S = 0\Omega$				15		
	Voltage noise					11		nV/√Hz
	Tonago noise		f = 1kHz			11		
			f _B = 0.1Hz t	o 10Hz		0.4		μV_{PP}
		f = 10Hz				0.4		pA/√Hz
	Noise current	f = 1kHz				0.2		pA/√Hz
		f _B = 0.1Hz to 10Hz				18		pA_{PP}

5.5 Electrical Characteristics (continued)

at T_A = 25°C, V_S = ±15V, R_L = 2k Ω , V_{REF} = 0V, and G = 1 (unless otherwise noted)

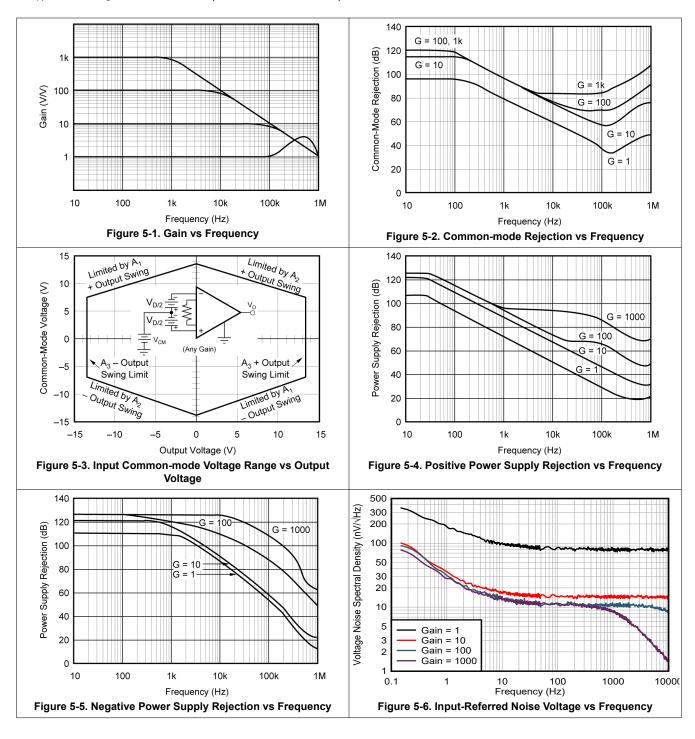
	PARAMETER	TEST CO	NDITIONS		MIN	TYP	MAX	UNIT	
GAIN									
G	Gain equation				1	+ (50kΩ / R _G)		V/V	
	Range of gain				1		10000	V/V	
		V _O = ±10V, G = 1				±0.01	±0.05		
				INA114BP, BU		±0.02	±0.4		
			G = 10	INA114AP, AU		±0.02	±0.5		
GE	Gain error	V = 140V	0 100	INA114BP, BU		±0.05	±0.5	%	
		V _O = ±10V	G = 100	INA114AP, AU		±0.05	±0.7		
			0 - 4000	INA114BP, BU		±0.5	±1		
			G = 1000	INA114AP, AU		±0.5	±2		
	Cain duit					±2	±10	/00	
	Gain drift	$R_S = 50k\Omega^{(1)}$				±25	±100	ppm/°C	
			G = 1	INA114BP, BU		±0.0001	±0.001		
			G = 1	INA114AP, AU		±0.0001	±0.002		
	Gain nonlinearity	\/ = 10\/ to 110\/	G = 10, 100	INA114BP, BU		±0.0005	±0.002	% of FSR	
	Gain nonlinearity	$V_0 = -10V \text{ to } +10V$	G = 10, 100	INA114AP, AU		±0.0005	±0.004	% 01 FSR	
			G = 1000	INA114BP, BU		±0.002	±0.01		
			G = 1000	INA114AP, AU		±0.002	±0.02		
OUTP	JT			•					
					(V-) +1.5		(V+) -1.5		
	Output voltage	$I_{O} = 5$ mA, $T_{A} = -40$ °C to 85°C	V _S = ±11.4V		(V-) + 1.4		(V+) - 1.4	V	
			$V_S = \pm 2.25 V$		(V-) +1		(V+) – 1		
	Load capacitance stability					1000		pF	
I _{SC}	Short-circuit current	Continuous to V _S / 2				+20 / –15		mA	
FREQ	JENCY RESPONSE								
		G = 1				1		MHz	
BW	Dandwidth 2dD	G = 10				100			
DVV	Bandwidth, –3dB	G = 100				10		kHz	
	G = 1000					1			
SR	Slew rate	G = 10, V _O = ±10V			0.3	0.6		V/µs	
			G = 1			18			
	Cattling time	0.040/ \/ = 40\/	G = 10	G = 10		20			
t _S	Settling time	0.01%, V _{STEP} = 10V G = 100 G = 1000		G = 100		120		μs	
						1100			
	Overload recovery	50% overdrive				20		μs	
POWE	R SUPPLY								
IQ	Quiescent current	$V_S = \pm 2.25 V$ to $\pm 18 V$, $V_{IN} = 0 V$				±2.2	±3	mA	
		1			i contract of the contract of				

⁽¹⁾ Temperature coefficient of the "50k $\!\Omega\!$ " term in the gain equation.



5.6 Typical Characteristics

at $T_A = +25$ °C, $V_S = \pm 15$ V, G = 1V/V (unless otherwise noted)

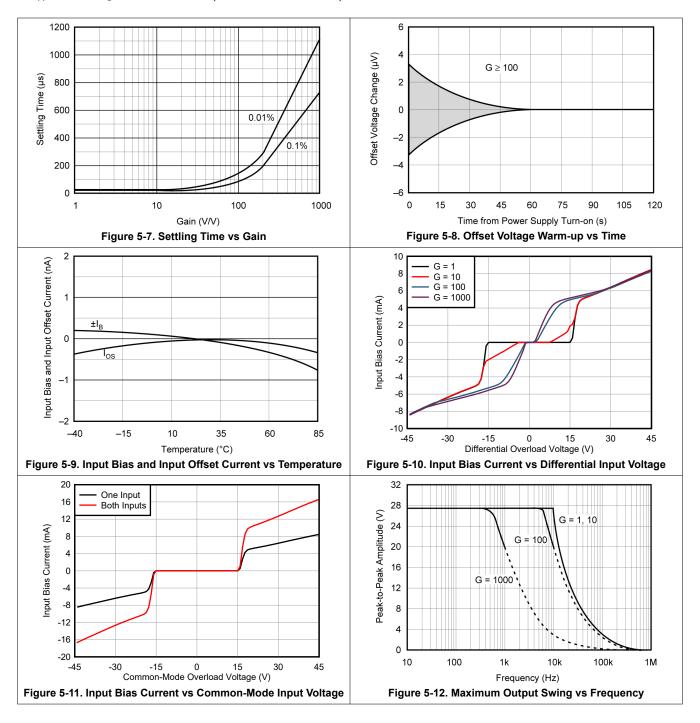


Submit Document Feedback

Copyright © 2024 Texas Instruments Incorporated

5.6 Typical Characteristics (continued)

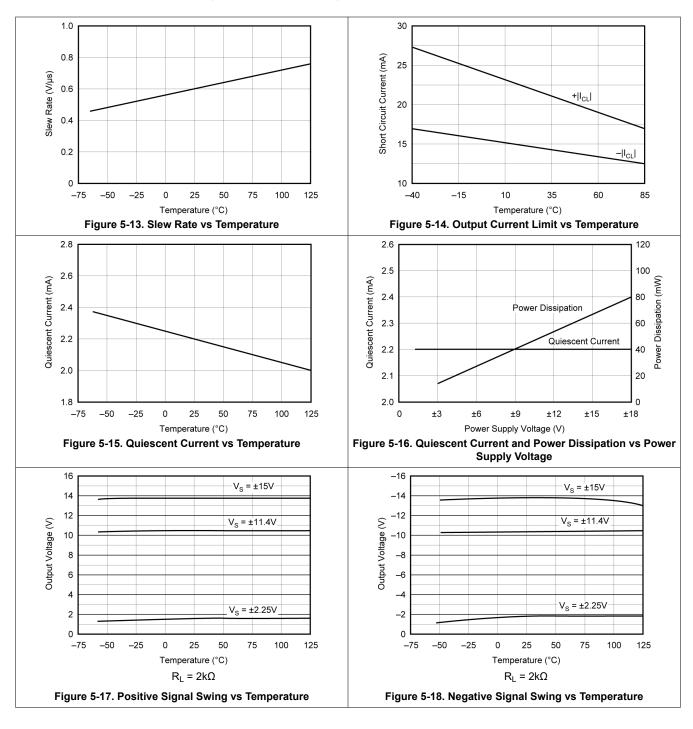
at $T_A = +25$ °C, $V_S = \pm 15$ V, G = 1V/V (unless otherwise noted)





5.6 Typical Characteristics (continued)

at $T_A = +25$ °C, $V_S = \pm 15$ V, G = 1V/V (unless otherwise noted)

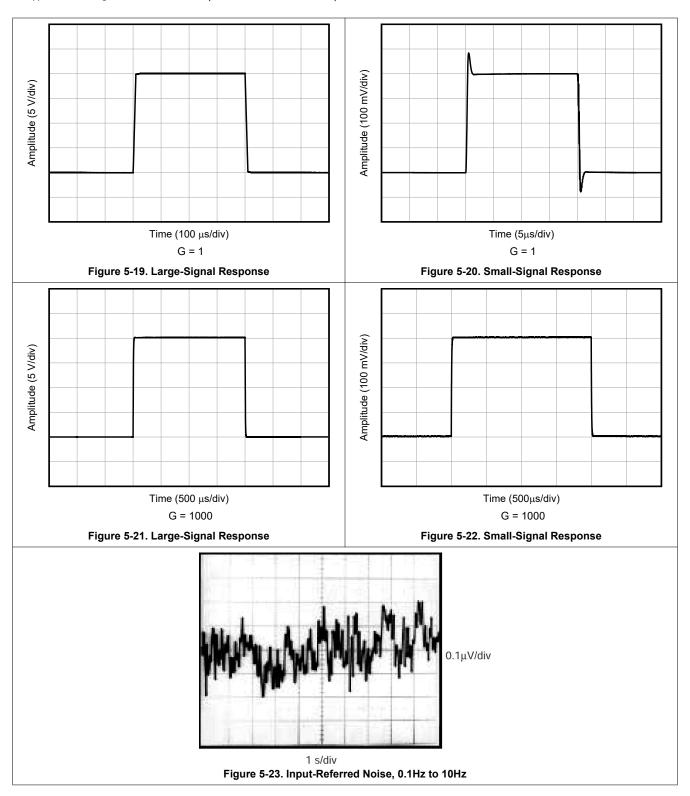


Submit Document Feedback

Copyright © 2024 Texas Instruments Incorporated

5.6 Typical Characteristics (continued)

at $T_A = +25$ °C, $V_S = \pm 15$ V, G = 1V/V (unless otherwise noted)



6 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

6.1 Application Information

Figure 6-1 shows the basic connections required for operation of the INA114. Applications with noisy or high-impedance power supplies can require decoupling capacitors close to the device pins as shown.

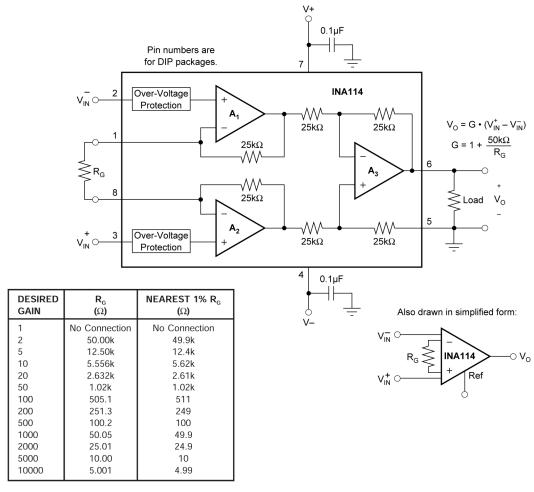


Figure 6-1. Basic Connections.

The output is referred to the output reference (Ref) pin, which is normally grounded. This connection must be low-impedance to provide good common-mode rejection. A resistance of 5Ω in series with the Ref pin causes a typical device to degrade to approximately 80dB CMR (G = 1).

Product Folder Links: INA114

6.1.1 Setting the Gain

Gain of the INA114 is set by connecting a single external resistor, R_G:

$$G = 1 + \frac{50 \,\mathrm{k}\Omega}{\mathrm{R}_{\mathrm{G}}} \tag{1}$$

Figure 6-1 shows commonly used gains and resistor values.

The 50-k Ω term in Equation 1 comes from the sum of the two internal feedback resistors. These resistors are on-chip metal film resistors which are laser trimmed to accurate absolute values. The accuracy and temperature coefficient of these resistors are included in the gain accuracy and drift specifications of the INA114.

The stability and temperature drift of the external gain setting resistor, R_G , also affects gain. The contribution of R_G to gain accuracy and drift is directly inferred from the gain Equation 1. Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance, which contributes additional gain error (possibly an unstable gain error) in gains of approximately 100 or greater.

6.1.2 Noise Performance

The INA114 provides very low noise in most applications. For differential source impedances less than $1k\Omega$, the INA103 can provide lower noise. For source impedances greater than $50k\Omega$, the INA111 FET-input instrumentation amplifier can provide lower noise.

Low frequency noise of the INA114 is approximately $0.4\mu V_{PP}$ measured from 0.1Hz to 10Hz. This noise is approximately one-tenth the noise of *low noise* chopper-stabilized amplifiers.

6.1.3 Offset Trimming

The INA114 is laser trimmed for very low offset voltage and drift. Most applications require no external offset adjustment. Figure 6-2 shows an optional circuit for trimming the output offset voltage. The voltage applied to the Ref pin is summed at the output. Maintain low impedance at this node to maintain good common-mode rejection by buffering trim voltage with an op amp as shown.

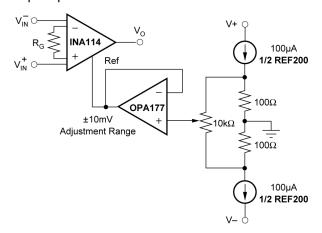


Figure 6-2. Optional Trimming of Output Offset Voltage.

6.1.4 Input Bias Current Return Path

The input impedance of the INA114 is extremely high-approximately $10^{10}\Omega$. However, a path must be provided for the input bias current of both inputs. This input bias current is typically less than ± 1 nA, and can be either polarity as a result of cancellation circuitry. High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current if the INA114 is to operate properly. Figure 6-3 shows various provisions for an input bias current path. Without a bias current return path, the inputs float to a potential that exceeds the common-mode range of the INA114 and the input amplifiers saturate. If the differential source resistance is low, the bias current return path can be connected to one input (see thermocouple example in Figure 6-3). With higher source impedance, use two resistors to provide a balanced input, with the possible advantages of lower input offset voltage due to bias current and better common-mode rejection.

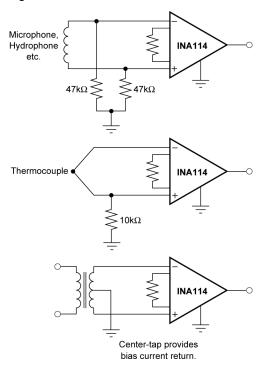


Figure 6-3. Providing an Input Common-Mode Current Path.

Submit Document Feedback

Copyright © 2024 Texas Instruments Incorporated

6.1.5 Input Common-Mode Range

The linear common-mode range of the input op amps of the INA114 is approximately ± 13.75 V (or 1.25V from the power supplies). As the output voltage increases, however, the linear input range is limited by the output voltage swing of the input amplifiers, A_1 and A_2 . The common-mode range is related to the output voltage of the complete amplifier—see typical characteristic curve *Input Common-Mode Range vs Output Voltage*.

A combination of common-mode and differential input signals can cause the output of A_1 or A_2 to saturate. Figure 6-4 shows the output voltage swing of A_1 and A_2 expressed in terms of a common-mode and differential input voltages. Output swing capability of these internal amplifiers is the same as the output amplifier, A_3 . For applications where input common-mode range must be maximized, limit the output voltage swing by connecting the INA114 in a lower gain (see performance curve *Input Common-Mode Voltage Range vs Output Voltage*). If necessary, add gain after the INA114 to increase the voltage swing.

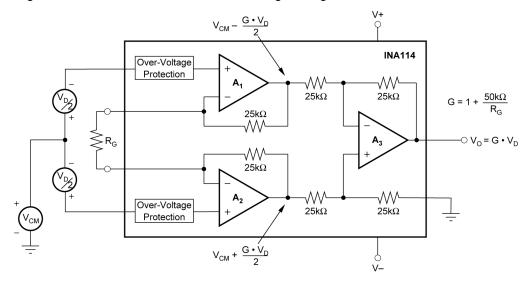


Figure 6-4. Voltage Swing of A₁ and A₂

Input overload often produces an output voltage that appears normal. For example, an input voltage of 20V on one input and 40V on the other input obviously exceeds the linear common-mode range of both input amplifiers. Both input amplifiers are saturated to nearly the same output voltage limit; therefore, the difference voltage measured by the output amplifier is near zero. The output of the INA114 is near 0V even though both inputs are overloaded.

6.1.6 Input Protection

The inputs of the INA114 are individually protected for voltages up to ±40V. For example, a condition of –40V on one input and +40V on the other input does not cause damage. Internal circuitry on each input provides low series impedance under normal signal conditions. To provide equivalent protection, series input resistors contribute excessive noise. If the input is overloaded, the protection circuitry limits the input current to a safe value (approximately 1.5mA). Typical performance curve *Input Bias Current vs Common-Mode Input Voltage* shows this input current limit behavior. The inputs are protected even if no power supply voltage is present.

Copyright © 2024 Texas Instruments Incorporated

Submit Document Feedback

6.1.7 Output Voltage Sense (SOIC-16 Package Only)

The surface-mount version of the INA114 has a separate output sense feedback connection (pin 12). Pin 12 must be connected to the output terminal (pin 11) for proper operation. (This connection is made internally on the DIP version of the INA114.)

The output sense connection can be used to sense the output voltage directly at the load for best accuracy. Figure 6-5 shows how to drive a load through series interconnection resistance. Remotely located feedback paths can cause instability. This instability can be generally be eliminated with a high-frequency feedback path through C₁. Drive heavy loads or long lines by connecting a buffer inside the feedback path (see Figure 6-6).

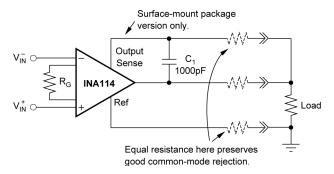


Figure 6-5. Remote Load and Ground Sensing

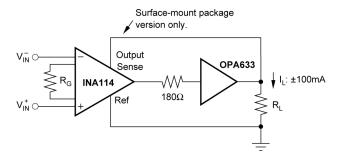


Figure 6-6. Buffered Output for Heavy Loads

Submit Document Feedback

Copyright © 2024 Texas Instruments Incorporated



7 Typical Applications

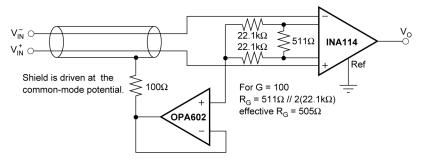


Figure 7-1. Shield Driver Circuit

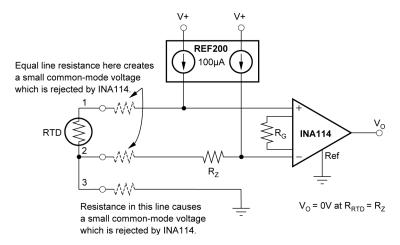
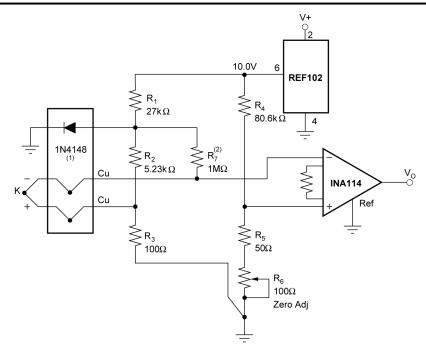


Figure 7-2. RTD Temperature Measurement Circuit





ISA TYPE	MATERIAL	SEEBECK COEFFICIENT (µV/°C)	R_2 ($R_3 = 100\Omega$)	R_4 (R ₅ + R ₆ = 100 Ω)
Е	Chromel Constantan	58.5	3.48kΩ	56.2kΩ
J	Iron Constantan	50.2	4.12kΩ	64.9kΩ
К	Chromel Alumel	39.4	5.23kΩ	80.6kΩ
Т	Copper Constantan	38.0	5.49kΩ	84.5kΩ

NOTES: (1) -2.1mV/°C at 200 μ A. (2) R₇ provides down-scale burn-out indication.

Figure 7-3. Thermocouple Amplifier with Cold Junction Compensation

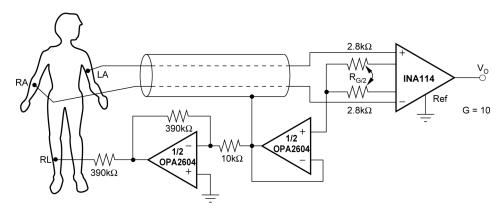


Figure 7-4. ECG Amplifier with Right-Leg Drive

Submit Document Feedback

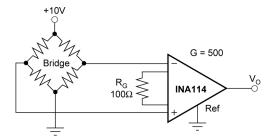


Figure 7-5. Bridge Transducer Amplifier

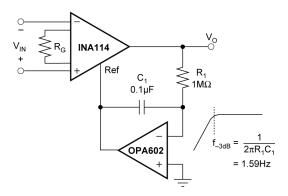
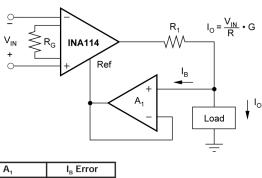


Figure 7-6. AC-Coupled Instrumentation Amplifier



 A1
 IB Error

 OPA177
 ±1.5nA

 OPA602
 1pA

 OPA128
 75fA

Figure 7-7. Differential Voltage-to-Current Converter



8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on Notifications to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.2 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.5 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

С	hanges from Revision * (March 1998) to Revision A (January 2024)	Page
•	Updated the numbering format for tables, figures, and cross-references throughout the document	1
•	Added the ESD Ratings, Recommended Operating Conditions, Thermal Information, Application and	
	Implementation, Typical Applications, Device and Documentation Support, and Mechanical, Packaging,	and
	Orderable Information sections	1
•	Changed SOL package name to SOIC throughout data sheet	1
•	Added "for high gains" to low offset voltage and low drift bullets in Features	1
•	Changed low drift bullet value from 0.25µV/°C to 0.3µV/°C in Features	1
•	Updated bullets in Applications	1
•	Added symbols in Absolute Maximum Ratings	3
•	Changed supply voltage to show dual supply and single supply in Absolute Maximum Ratings	3
•	Changed "Input Voltage Range" to "Signal input pins" in Absolute Maximum Ratings	3
•	Added signal output voltage to Absolute Maximum Ratings	3
•	Changed output short-circuit from "ground" to "V _S / 2" in Absolute Maximum Ratings	3
•	Added DW (SOIC) package ambient thermal resistance value	3
•	Changed ambient thermal resistance value for P (PDIP) package from 80°C/W to 110.2°C/W	3
•	Added symbols in Electrical Characteristics	4
•	Changed offset voltage maximum value from ±50 + 100/G to ±50 + 150/G	4
•	Changed "Offset Voltage vs Temperature" to "Offset voltage drift"	4
•	Changed offset voltage drift test condition from $T_A = T_{MIN}$ to T_{MAX} to $T_A = -40$ °C to +85°C	4

Product Folder Links: INA114

www.ti.com

•	Changed offset voltage drift maximum value from ±0.25 + 5/G to ±0.3 + 5/G	4
•	Deleted safe input voltage from Electrical Characteristics	4
•	Changed "Input Common-Mode Range" to "Operating input voltage"	
•	Changed "Offset Voltage vs Power Supply" to "Power-supply rejection ratio"	
•	Changed "Bias current vs Temperature" to "Input bias current drift"	
•	Added "T _A = -40°C to +85°C" test condition to input bias current drift	
•	Changed "Offset Current vs Temperature" to "Input offset current drift"	
•	Added "T _A = -40°C to +85°C" test condition to input offset current drift	4
	Added "V _O = ±10V" test condition to gain error	
•	Changed "Gain vs Temperature" to "Gain drift"	4
•	Added "V _O = -10V to +10V" test condition to gain nonlinearity	4
•	Changed output voltage values from ±13.5 (min) and ±13.7 (typ) to (V-) + 1.5 (min) and (V+) - 1.5 (max)	4
•	Changed output voltage test condition from T_{MIN} to T_{MAX} to $T_{A} = -40^{\circ}$ C to +85°C	4
•	Added output voltage test conditions for $V_S = \pm 11.4V$ and $V_S = \pm 2.25V$	4
•	Added V _{STEP} = 10V test condition to settling time	4
•	Deleted power supply voltage range typical value of ±15V	4
•	Moved voltage range, operating temperature range, and thermal resistance from <i>Electrical Characteristics</i> to	
	Recommended Operating Conditions and Thermal Information	4
•	Updated Figure 5-6, Input-referred Noise Voltage vs Frequency	6
•	Updated Figure 5-10, Input Bias Current vs Differential Input Voltage	6
•	Updated Figure 5-11, Input Bias Current vs Common-Mode Input Voltage	6
•	Updated Figure 5-19 to Figure 22, Small- and Large-Signal Response plots	6

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

www.ti.com 9-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
INA114AP	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-	INA114AP
INA114AP.B	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	INA114AP
INA114AU	Active	Production	SOIC (DW) 16	40 TUBE	Yes	Call TI Nipdau	Level-3-260C-168 HR	-40 to 85	INA114AU
INA114AU.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	INA114AU
INA114AU/1K	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	Call TI Nipdau	Level-3-260C-168 HR	-40 to 85	INA114AU
INA114AU/1K.B	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	INA114AU
INA114BP	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-	INA114BP
INA114BP.B	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	INA114BP
INA114BU	Active	Production	SOIC (DW) 16	40 TUBE	Yes	Call TI Nipdau	Level-3-260C-168 HR	-	INA114BU
INA114BU.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	INA114BU
INA114BU/1K	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	Call TI Nipdau	Level-3-260C-168 HR	-	INA114BU
INA114BU/1K.B	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	INA114BU

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

www.ti.com 9-Nov-2025

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA114AU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
INA114BU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

www.ti.com 24-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA114AU/1K	SOIC	DW	16	1000	353.0	353.0	32.0
INA114BU/1K	SOIC	DW	16	1000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TUBE



*All dimensions are nominal

7 til dilliciololio die Hollindi								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
INA114AP	Р	PDIP	8	50	506	13.97	11230	4.32
INA114AP.B	Р	PDIP	8	50	506	13.97	11230	4.32
INA114AU	DW	SOIC	16	40	507	12.83	5080	6.6
INA114AU.B	DW	SOIC	16	40	507	12.83	5080	6.6
INA114BP	Р	PDIP	8	50	506	13.97	11230	4.32
INA114BP.B	Р	PDIP	8	50	506	13.97	11230	4.32
INA114BU	DW	SOIC	16	40	507	12.83	5080	6.6
INA114BU.B	DW	SOIC	16	40	507	12.83	5080	6.6

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025